



Material Content Data Sheet



Halogen-Free

Sales Product Name	IKB20N65EH5	Issued	24. February 2022
MA#	MA005708643		
Package	PG-TO263-3-2	Weight*	1559.89 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.970	0.06	0.06	622	622
chip_2	inorganic material	silicon	7440-21-3	1.263	0.08	0.08	810	810
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.49	19.52	194902	195156
wire	non noble metal	aluminium	7429-90-5	7.490	0.48	0.48	4802	4802
encapsulation	inorganic material	zinc oxide	1314-13-2	6.847	0.44		4389	
	miscellaneous	miscellaneous	-	27.388	1.76		17558	
	plastics	epoxy resin	-	102.705	6.58		65841	
	inorganic material	silicon dioxide	60676-86-0	547.758	35.12	43.90	351150	438938
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6191	6191
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.056			36	
	noble metal	silver	7440-22-4	0.070			45	
	non noble metal	lead	7439-92-1	2.657	0.17	0.17	1703	1784
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		352	
	non noble metal	copper	7440-50-8	547.666	35.11	35.16	351093	351550
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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